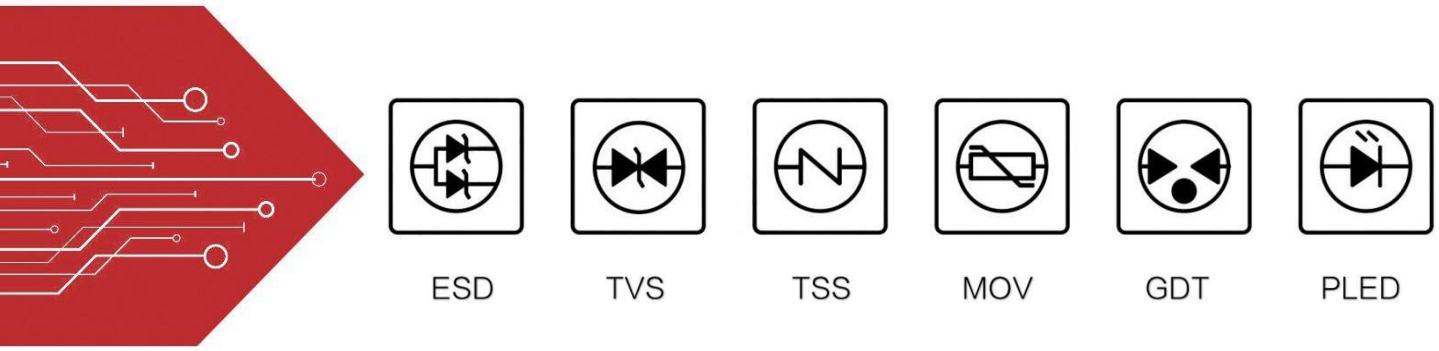
MSKSEMI
SEMICONDUCTOR



Product data sheet

Feature

Ultra Small mold type. SOD-923

Low I_R

High reliability.

SOD-923

Applications

Low current rectification

Mechanical Characteristics

Lead finish:100% matte Sn(Tin)

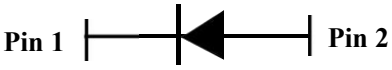
Mounting position: Any

Qualified max reflow temperature:260℃

Device meets MSL 1 requirements

Pure tin plating: 7 ~ 17 um

Pin flatness：≤3mil



Circuit Diagram

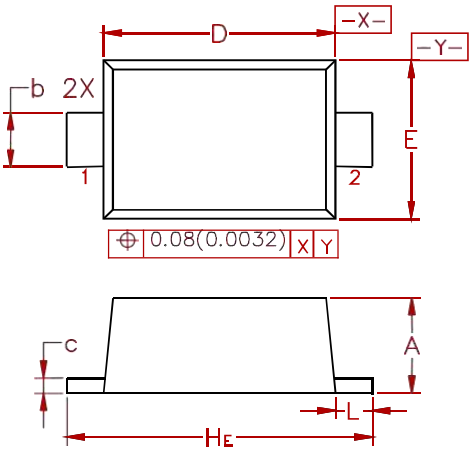
Electrical characteristics per line@25℃

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Forward voltage	V_F	-	0.27	0.31	V	I_F=1mA
Forward voltage	V_F	-	0.30	0.35	V	I_F=10mA
Forward voltage	V_F		0.36	0.40	V	I_F=20mA
Forward voltage	V_F	-	0.48	0.55	V	I_F=100mA
Reverse current	I_R	-	-	1.5	μA	V_R=10V

Absolute maximumrating@25℃

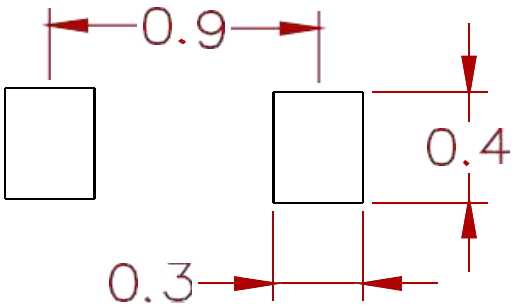
Parameter	Symbol	limits	Unit
Reverse voltage (DC)	V_{RM}	30	V
Average rectified forward current	I_o	100	mA
Forward current surge peak (60Hz 1cyc)	I_{FSM}	500	mA
Operating Junction temperature Range	T_j	-55 to 125	℃
Storage temperature	T_{stg}	-40 to +125	℃

PACKAGE MECHANICAL DATA



Dim	Millimeters			Inches		
	Min	Nom	Max	Min	Nom	Max
A	0.36	0.40	0.43	0.014	0.016	0.017
b	0.15	0.20	0.25	0.006	0.008	0.010
c	0.07	0.12	0.17	0.003	0.005	0.007
D	0.75	0.80	0.85	0.030	0.031	0.033
E	0.55	0.60	0.65	0.022	0.024	0.026
HE	0.95	1.00	1.05	0.037	0.039	0.041
L	0.05	0.10	0.15	0.002	0.004	0.006

Suggested Pad Layout



Dimensions: Millimeters

REEL SPECIFICATION

P/N	PKG	QTY
RB521CS-30-MS	SOD-923	8000

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